

What Is Claimed Is:

1. A method of fabricating a liquid crystal display device, comprising:
 - providing a cliché having a plurality of grooves, each of the grooves having different depths and widths;
 - filling resist material into the plurality of grooves;
 - transferring the resist filled in the grooves onto a printing roll to form a plurality of resist portions along a circumference of the printing roll; and
 - applying the resist portions onto a surface of an etching layer,
 - wherein the applied resist portions form a resist pattern along the surface of the etching layer.
2. The method according to claim 1, wherein the plurality of grooves are formed in the cliché by at least two photolithographic processes.
3. The method according to claim 1, wherein the step of providing the cliché comprises:
 - providing a substrate;
 - depositing an organic layer onto a surface of the substrate;
 - applying and patterning a first photoresist on the organic layer;

forming at least one first groove in the organic layer by etching the organic layer using the first photoresist as a first mask;
removing portions of the first photoresist;
forming a second photoresist pattern on the organic layer and the at least one first groove;
forming at least one second groove in the organic layer by etching the organic layer using the second photoresist pattern as a second mask; and
removing portions of the second photoresist.

4. The method according to claim 3, wherein the organic layer includes at least one of polymers and polyimides.

5. The method according to claim 3, wherein the substrate includes at least one of glass and plastic.

6. The method according to claim 1, wherein the step of providing the cliché comprises:

preparing a substrate;
depositing a metal layer onto the substrate;
forming a first photoresist on the metal layer;

forming at least one first groove in the metal layer by etching the metal layer using the first photoresist pattern as a first mask;

forming a second photoresist pattern on the metal layer and the at least one first groove;

forming at least one second groove in the metal layer by etching the metal layer using the second photoresist pattern as a second mask; and

removing portions of the second photoresist pattern.

7. The method according to claim 1, wherein the step of filling the resist material into the plurality of grooves of the cliché comprises:

depositing the resist material onto a surface and the grooves of the cliché;

and

removing the resist material deposited on the surface of the cliché using a blade.

8. The method according to claim 1, wherein the etching object layer includes at least one of SiO_x and SiN_x.

9. The method according to claim 1, wherein the etching object layer includes at least a metal layer.

10. A method for fabricating a liquid crystal display (LCD) device, comprising:

- preparing one of a glass and plastic substrate;
- forming a plurality of grooves in the substrate, each of the grooves having different depths and widths;
- filling resist material into the plurality of grooves;
- transferring the resist material filled in the plurality of grooves onto a printing roll to form a plurality of resist portions;
- applying the plurality of resist portions onto an etching object layer to form a resist pattern; and
- etching the etching object layer using the resist pattern as a mask.

11. A method for fabricating a liquid crystal display (LCD) device, comprising:

- preparing one of a glass and plastic substrate;
- depositing an organic layer onto the substrate;
- forming a plurality of grooves through a surface of the organic layer, each of the grooves having different depths and widths;
- depositing resist material on the surface and plurality of grooves of the organic layer;
- removing portions of the resist material deposited on the surface of the organic layer using a blade;

transferring the resist material filled in the grooves onto a printing roll to form a plurality of resist portions; and

applying the resist portions formed on the printing roll onto an etching object layer.

12. A method for fabricating a liquid crystal display (LCD) device, comprising:

providing a first substrate;

forming a plurality of first grooves through a surface of the first substrate, each first groove having a first depth and a first width;

forming a plurality of second grooves through the surface of the first substrate, each second groove having a second depth smaller than the first depth and a second width larger than the first width;

filling resist material into the plurality of first and second grooves;

attaching an etching object substrate onto the surface of the first substrate;

applying at least one of heat and pressure to the etching object substrate;

and

applying the resist material filled in the first and second grooves onto the etching object substrate by separating the etching object substrate from the first substrate to form a resist pattern on the etching object substrate having a plurality

of first portions corresponding to the plurality of first grooves and a plurality of second resist portions corresponding to the plurality of second grooves,

wherein a first thickness of the first resist portions is larger than a second thickness of the second resist portions.

13. The method according to claim 12, wherein a first width of the first resist portions is smaller than a second width of the second resist portions.

14. The method according to claim 13, wherein the first thickness of the first resist portions is approximately equal to the first depth of the plurality of first grooves and the second thickness of the second resist portions is approximately equal to the second depth of the plurality of second grooves.

15. The method according to claim 12, wherein the step of filling the resist material comprises:

depositing the resist material onto the surface and plurality of first and second grooves in the first substrate;

removing the resist material deposited on the surface of the first substrate using a blade.

16. The method according to claim 12, wherein the etching object substrate includes at least one of SiO_x and SiN_x.

17. The method according to claim 12, wherein the etching object substrate includes at least a metal layer.